

# Zhen Ding Technology Holding (4958 TT)

First Quarter of 2024 Investor Conference

May 10<sup>th</sup>, 2024



### **Safe Harbor Notice**

- Zhen Ding Technology Holding's statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



# AGENDA

## **1Q24 Financial Results**

Eddie Chiang, Chief Financial Officer

## **Company Strategy**

Charles Shen, Chairman

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## **IC Substrate Business Update**

D.J. Lee, Director & Chief Operating Officer



# **1Q24 Financial Results**

### Eddie Chiang, Chief Financial Officer





### **1Q24 Financial Results**

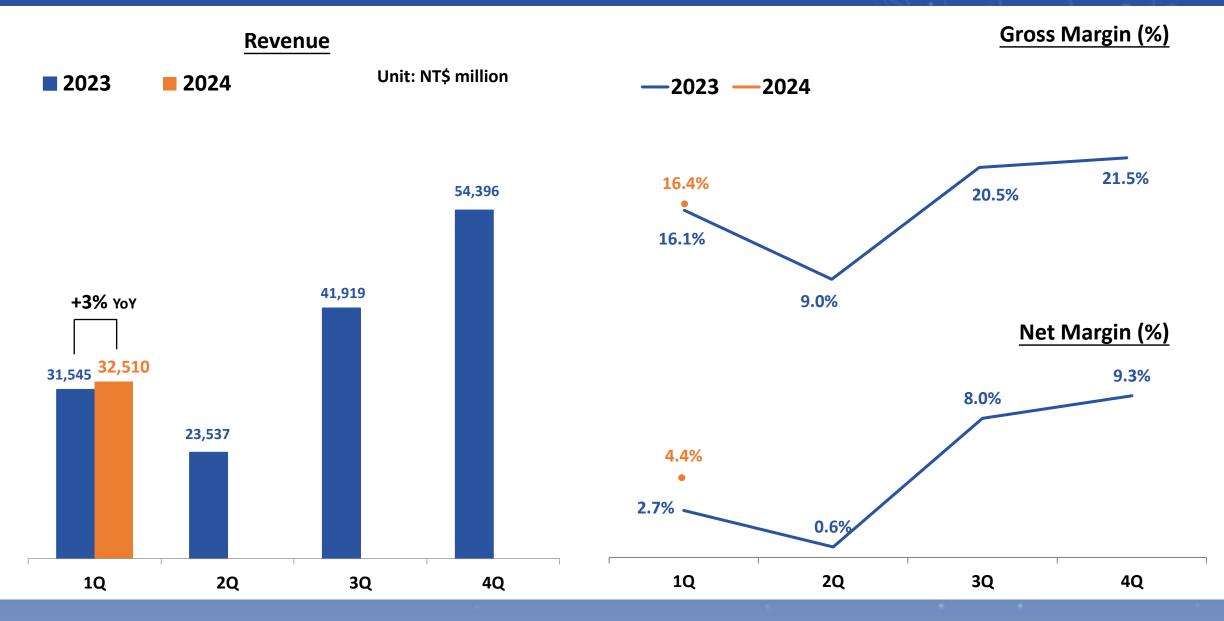
(Unit: NT\$ million, unless otherwise stated)

	1Q24	1Q23	YoY (%)
Revenue	32,510	31,545	3.1%
Gross Profit	5,337	5,075	5.2%
Gross Margin	16.4%	16.1%	+0.3ppts
Operating Expense	4,594	3,857	19.1%
Operating Profit	743	1,219	-39.1%
Operating Margin	2.3%	3.9%	-1.6ppts
Non-Operating Income/Expense	755	(318)	
Net Income	1,436	863	66.4%
Net Margin	4.4%	2.7%	+1.7ppts
Net Income to Parent	977	504	94.1%
EPS (NT\$) <sup>(1)</sup>	1.03	0.53	
R&D Expense	2,634	1,939	+35.9%
Depreciation and Amortization	4,231	3,958	+6.9%
Cash Inflow Generated from Operations	8,262	11,746	-29.7%
Cash and Cash Equivalents <sup>(2)</sup>	72,995	68,703	6.2%
ROE(%) <sup>(3)</sup>	4.2%	2.6%	+1.6ppts

Note : (1) Weighted Average Shares outstanding as of 1Q24 : 944,956 thousand shares (actual issuance 947,049 thousand shares, with 2,093 thousand shares held in treasury (2) Including current financial assets at amortized cost (time deposits, etc.) (3) ROE is annualized data calculated based on the average of equity attributable to owners of parent

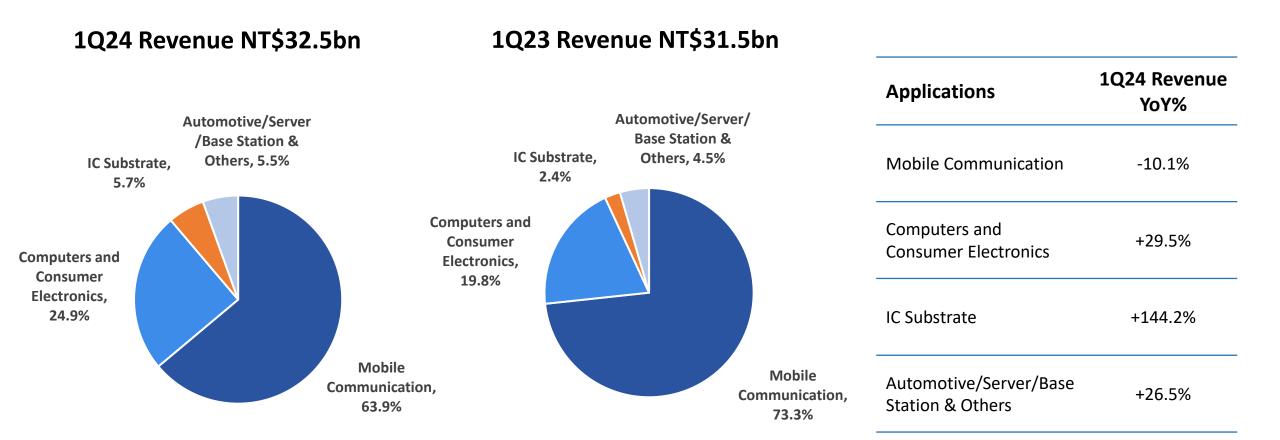


### **Quarterly Operation Results**





### **Revenue Breakdown – By Applications**



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### **Consolidated Balance Sheet and Key Indices**

	2024-3-3	31	2023-3-3	31	Unit: NT\$ million Change			
-	Amount	%	Amount	%	Amount	%		
Cash and Cash Equivalents <sup>(2)</sup>	72,995	30.0%	68,703	29.7%	4,292	6.25%		
Notes & Accounts Receivable	20,856	8.6%	19,062	8.2%	1,794	9.41%		
Inventories	15,858	6.5%	13,985	6.0%	1,873	13.39%		
Property, Plant and Equipment <sup>(3)</sup>	110,806	45.6%	108,666	47.0%	2,140	1.97%		
Total Assets	243,253	100.0%	231,417	100.0%	11,836	5.11%		
Debt	54,143	22.3%	50,255	21.7%	3,888	7.74%		
Notes & Accounts Payable	33,230	13.7%	34,625	15.0%	-1,395	-4.03%		
Total Liabilities	104,632	43.0%	101,592	43.9%	3,040	2.99%		
Total Equity	138,652	57.0%	129,824	56.1%	8,828	6.80%		
Key Indices								
A/R Turnover Days	70		71					
Inventory Turnover Days	57		59					
Current Ratio (x)	1.82		1.41					
PPE Turnover (x) <sup>(4)</sup>	1.18		1.18					

Note : (1) Weighted Average Shares outstanding as of 1Q24 : 944,956 thousand shares (actual issuance 947,049 thousand shares, with 2,093 thousand shares held in treasury (2) Including current financial assets at amortized cost (time deposits, etc.) (3) PPE includes investment property (4) PPE Turnover = annualized net revenue / average net property, plant and equipment



### 2014-2023 Financial Summary

Unit: NT\$ million

Period	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023
Revenue	75,954	85,738	82,393	109,238	117,913	120,068	131,279	155,022	171,356	151,398
Gross Profit	14,323	16,427	12,542	17,833	26,061	27,222	26,584	30,537	39,888	27,459
Net Income	6,735	7,731	3,456	6,772	11,536	12,402	11,508	13,694	20,535	9,432
Net Income to Parent	6,735	7,731	3,456	5,172	8,448	8,685	8 <i>,</i> 095	9,651	14,197	6,189
Depreciation & Amortization	4,293	4,850	5,295	5,679	6,820	7,955	8,405	11,875	14,638	16,323
EPS (NT\$)	9.12	9.80	4.29	6.43	10.50	9.93	8.90	10.21	15.02	6.550
DPS (NT\$)	3.67	4.50	2.20	3.30	4.46	4.50	4.50	5.00	6.00	3.275
Payout Ratio (%)	40.2%	45.9%	51.3%	51.3%	42.5%	45.3%	50.6%	49.0%	40.0%	50.0%
Cash and Cash Equivalents*	23,482	31,572	30,241	33,296	49,154	43,071	46,775	35,179	57,599	65,970
Property, Plant and Equipment	30,073	32,074	32,262	36,681	41,913	46,243	68,177	86,073	104,814	109,965
Capital	7,386	8,047	8,047	8,047	8,047	9,022	9,470	9,470	9,470	9,470
ROE (%)	23.33%	20.82%	8.59%	14.49%	17.30%	14.72%	11.84%	12.59%	16.67%	7.10%
Debt Ratio (%)	62.54%	53.70%	59.72%	55.33%	44.25%	35.41%	42.56%	42.01%	42.87%	44.67%

\* Including current financial assets at amortized cost (time deposits, etc.)



# **Company Strategy**

### **Charles Shen, Chairman**





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## **1Q24 Review and Outlook**

#### 1Q24 revenue increased by 3.06% YoY, resuming growth in operations:

In 1Q24, our revenue for <u>Computers and Consumer Electronics</u> and <u>Automotive/Server/Base Station</u> both achieved double-digit YoY growth, while revenue for IC substrates delivered triple-digit growth, reaching a record high for a single quarter. Consistent with our previous expectation, we will continue to optimize our product mix this year, aiming to further diversify our product portfolio under the One ZDT strategy.

### Revenue to resume growth in 2024, with accelerated growth expected in 2025. IC substrate, server and automotive are the main growth drivers:

Al server products have started contributing to our revenue since 2023, with increasing customer order allocations in 2024. For automotive applications, we have developed products for ADAS radar, domain control boards, and power batteries. Overall, we remain optimistic about achieving double-digit revenue growth in IC substrates, servers, and automotive applications in the coming years.

### For smartphone, computer and consumer electronics, we have a comprehensive product portfolio for foldable phone, AI smartphone and AI PC:

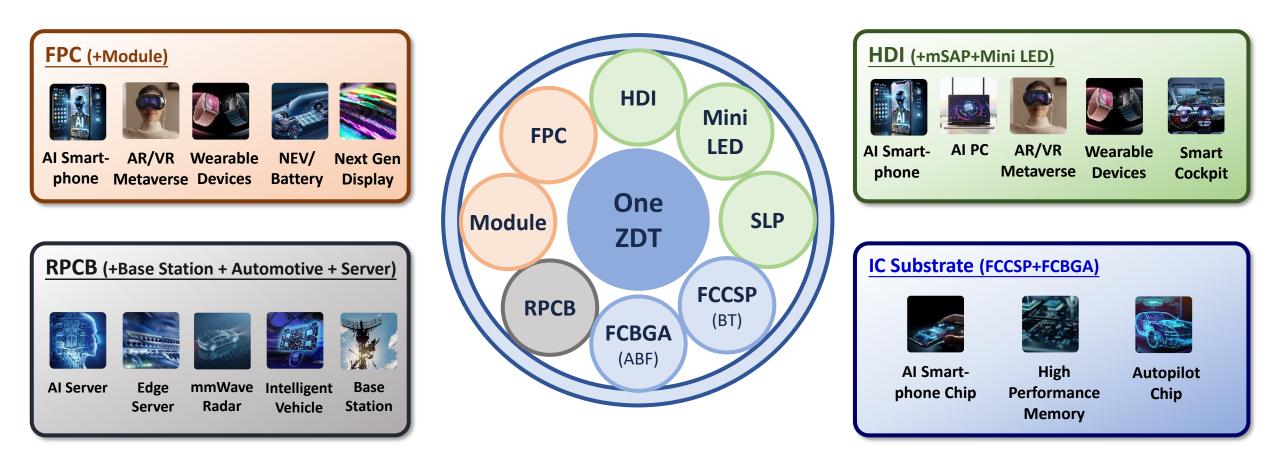
As a global leader in high-end PCBs, we have not only shipped products to multiple customers for foldable phones, but also actively collaborated with customers to develop products for AI smartphones and AI PCs. We expect the demand for high-end PCB with fine lines and high layer counts will continue to grow in the future.

#### The phase 1 of Thailand fab will focus on server, automotive, and optical applications, providing high-end RPCB/HDI products:

For the phase 1 of Thailand fab, we maintain our goal of entering trial production in 1H25 and mass production in small-scale in 2H25. Currently, the construction is progressing as planned. After the new capacity coming online, our global manufacturing footprint will be further enhanced.



### **One ZDT : One Stop Shopping Synergies**



The diversification of AI applications will increase design complexity for PCBs, driving growing demand for IC substrates, high-end HDI, and FPC.

### **Continued Effort to Diversify Product Portfolio**

#### ZDT's 1Q24 Revenue for Automotive/Server/Base Station Achieved 26.5% YoY Growth

Zhen Ding Tech. Holding

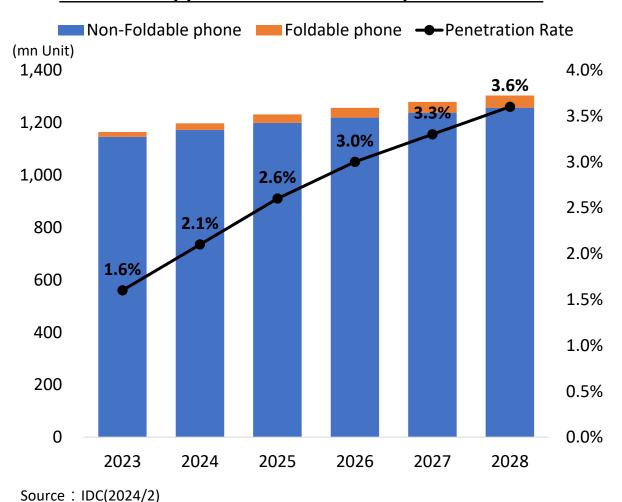
+26.5% YoY



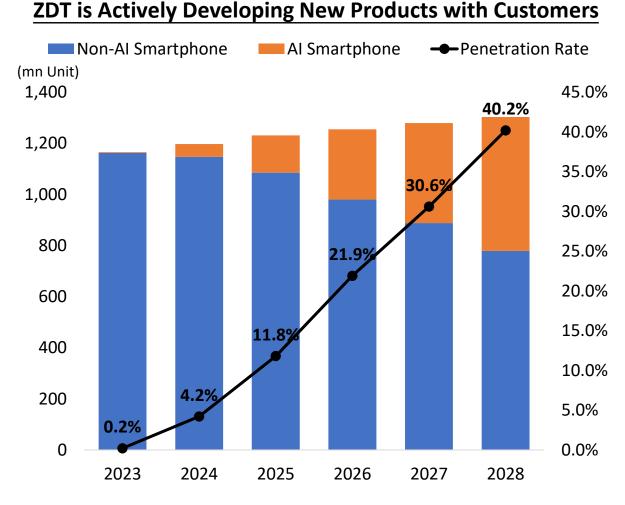
4Q22 1Q23 2Q23 1Q22 2Q22 3Q22 3Q23 4Q23 1Q24 **1Q22** 3Q22 4Q22 1Q23 2Q23 3Q23 4Q23 1Q24 2Q22

#### 臻鼎科技控版 Zhen Ding Tech. Holding High-end PCB Demand for Smartphones is on the Rise

#### **Global Foldable Smartphone Market:** ZDT has Shipped Products to Multiple Customers



#### Global AI Smartphone Market:



Source : IDC(2024/2)

#### 臻鼎科技控股 Zhen Ding Tech. Holding Construction of New Fab in Thailand is Progressing According to Plan



(Current) Thailand Prachinburi Park (Phase 1) : High-end RPCB/HDI



- The construction of the new fab in Prachinburi Province, Thailand is progressing according to plan, with the goal of trial production in 1H25 and mass production in small scale in 2H25.
- Phase 1 capacity will focus on server, automotive, and optical applications, providing high-end RPCB/HDI products.
- It will be ZDT's key manufacturing site in Southeast Asia.



2013

2014

2015

2016

2017

2018

2019

2020

2021

2022

2023

#### **Continued Capacity Expansion, Pursuing Stable Growth**

——Capex/Sales (%) Capex 20.1% 16.9% 17.2% 16.5% 31,149 13.8% 13.59 29,032 26,066 11.8% 11.7% 21,645 9.0% 7.3% 6.2% 16,224 16,211 12,747 9,682 7,755 5,580 4,012

- As the world's largest PCB manufacturer, we position ourself as a growth-oriented company. Adhering to our strategy of "Early Deployment", we proactively deploy our production capacity to meet customers' need.
- This year, we continue to invest in the construction of Kaohsiung and Thailand fabs, laying a solid foundation for long-term growth.



# IC Substrate Business Update

### D.J. Lee, Director & Chief Operating Officer

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## **IC Substrate Business Update**

#### IC substrate revenue marked a record high for a single quarter in 1Q24, entering a phase of rapid growth:

- In 1Q24, revenue contribution from IC substrates increased to 5.7% of total revenue. We maintain our goal of achieving a >50% revenue CAGR for IC substrate revenue to account for 15% +/- of total revenue.
- For BT substrates, utilization rate continues to increase, and the business has turned profitable for a single quarter. Automotive application has entered mass production:
  - Our BT substrates are primarily used in smartphone processors, memory, and RF applications, and we closely collaborate with top-tier customers. The utilization rate of our BT substrates exceeded 80% in 1Q24, and the business has turned profitable for a single quarter.
  - Fine line 6/8um Embedded Trace Substrate (ETS) is expected to enter mass production by the end of the year. Additionally, in 2024, the newly developed DDR-5 and NAND substrates will gradually enter mass production. Our yield is also on par with Tier 1 players.

ABF substrates have obtained customer qualifications and entered mass production. Revenue contribution from large body size substrates has been increasing. Both revenue and utilization rate are expected to increase quarter by quarter this year:

- In terms of ABF substrates, demand remains strong in AI and automotive applications. We are actively expanding the presence in these two major sectors by engaging customers. We have passed customer certifications and entered mass production, expecting both revenue and utilization rate to increase steadily quarter by quarter.
- We have provided high-end Chiplet substrates for customer qualification. We have shipped products with 18-20 layers and a maximum body size of 92mm x 92mm to customers, with yields being on par with Tier 1 ABF substrate suppliers, and these products have entered mass production. In addition, we have shipped 102mm x 102mm body size to customers for testing.
- We have a distinct advantage in fulfilling international customers' "China for China" demand:
- To increase market share, international customers need to gradually deploy local production capacity in the mainland China market. We have the most advanced IC substrate fabs in mainland China, which can fulfill international customers' "China for China" demand. This is our distinct advantage in the IC substrate industry.

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# **IC Substrate Capacity Expansion Plan**

		2023			2024				2025				2026								
		1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q				
	<b>Fab 1</b> (Mid to high- end products)		Instal	lation																	
SZ ABF Substrate Plant		Sa	ample ce	ertificati	on																
			Mass production, target yield: comparable to tier 1 peers									Full utilization, target yield: comparable to tier 1 peers									
(Two Fabs' floor area in total:	Fab 2												Installation								
170,000 m²)	(High end products)													Sa		ertificatio is produ					
QHD BT Substrate Plant (Two Fab's floor area in total: 60,000 m <sup>2</sup> )	Fab 1							Indu	stry Lea	ding Qu	ality				Mass production						
	Fab 2	Mass Production Utilization at 80%+ Industry Leading Quality																			



**IC Substrate Goals** 









#### **IC Substrate Capex:**

Plan to invest NT\$60bn from 2022~2027

#### **IC Substrate Revenue:**

2023~2027 Revenue CAGR >50%

#### **IC Substrate Revenue:**

Account for 15 %+/- of company's consolidated revenue in 2027

#### IC Substrate Market Share:

Aim to become one of the global top 5 companies in the IC substrate market in 2030



Q&A

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